

Material Declaration Report

Package Type:	TQFN 32L (3.0x6.0mm)
Pericom Package Code:	ZL32(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
REACH Compliance:	Yes
Halogen Free:	Yes

Component Weight (mg):	46.147
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	5/20/2010

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND G770HCD	24.003	UTL	Silica fuse	60676-86-0	90.500	21.7227
			Epoxy resin	Proprietary	4.500	1.0801
			Phenol resin	Proprietary	4.500	1.0801
			Carbon black	1333-86-4	0.500	0.1200
LEADFRAME Copper 194 PPF	17.550		Copper	7440-50-8	96.722	16.9746
			Iron	7439-89-6	2.210	0.3879
			Zinc	7440-66-6	0.137	0.0240
			Phosphorus	7723-14-0	0.035	0.0061
			Nickel	7440-02-0	0.859	0.1507
			Palladium	7440-05-3	0.029	0.0051
			Gold	7440-57-5	0.009	0.0016
SILICON DIE	3.750		Silicon (Si)	7440-21-3	99.192	3.7197
			Non-hazardous Metal	Proprietary	0.808	0.0303
DIE ATTACH EPOXY 8006NS	0.706		Treated Silica	14808-60-7	3.000	0.0212
			Glycol Ethers	Proprietary	22.000	0.1553
			Metal Oxide	Proprietary	32.000	0.2259
			Curing Agent & Hardener	Proprietary	8.000	0.0565
			Epoxy Resin	Proprietary	35.000	0.2471
GOLD WIRE	0.138		Gold(Au)	7440-57-5	99.990	0.1380
			Impurities	-	0.010	0.0000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	<p>Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium</p> <table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O	O
	Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm														
O	O	O	O	O	O														
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																			